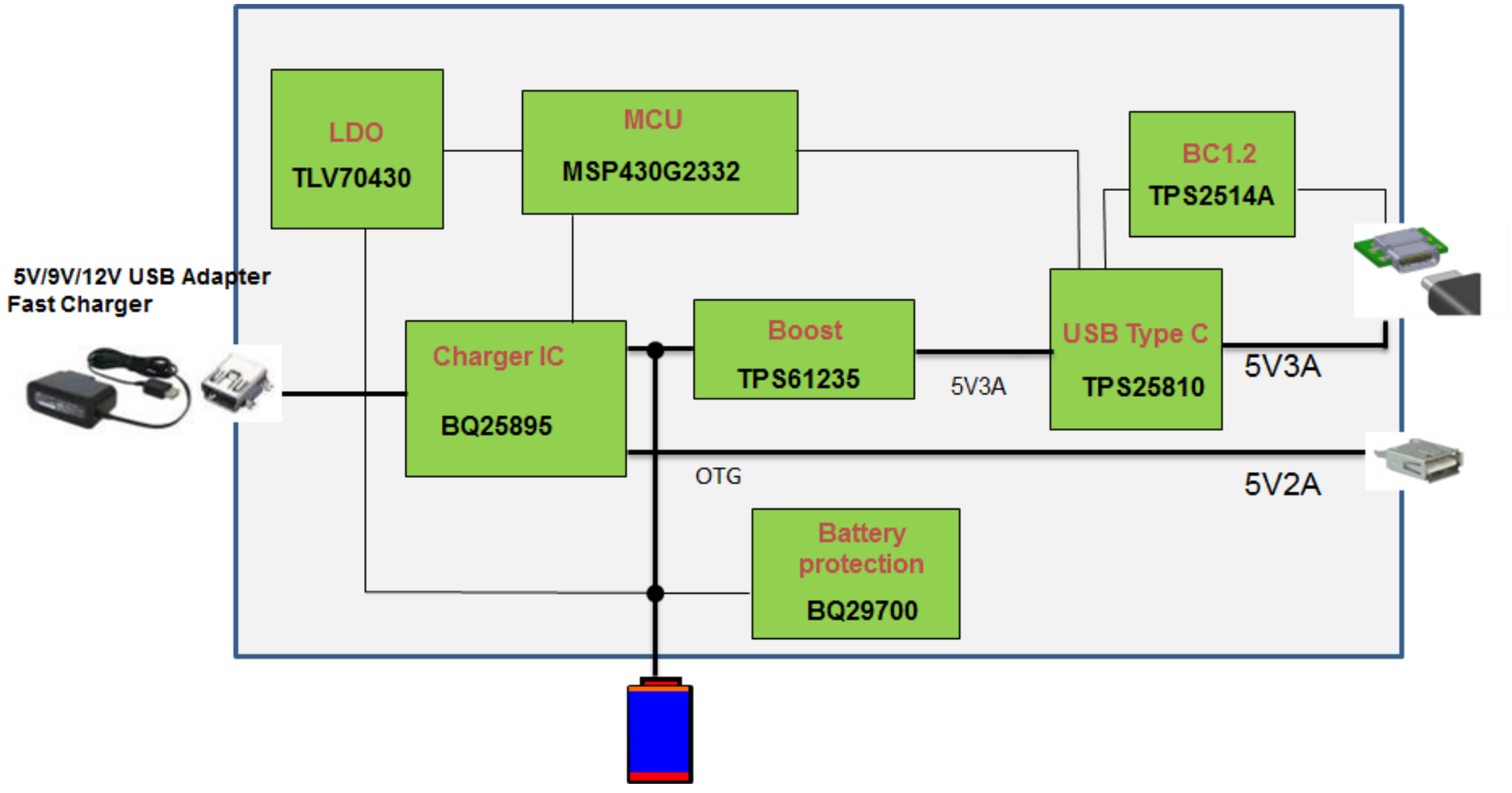
Revision History	
Revision	Notes
1.0	For Public Release



Orderable: N/A		Designed for: Public Release	Mod. Date: 11/3/2015
TID #: PM11536		Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	
Number: PMP11536	Rev: 1.0	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 1 of 3
Drawn By:		File: PMP11536_Cover.SchDoc	Size: B
Engineer: Yingyang Ou		Contact: http://www.ti.com/support	

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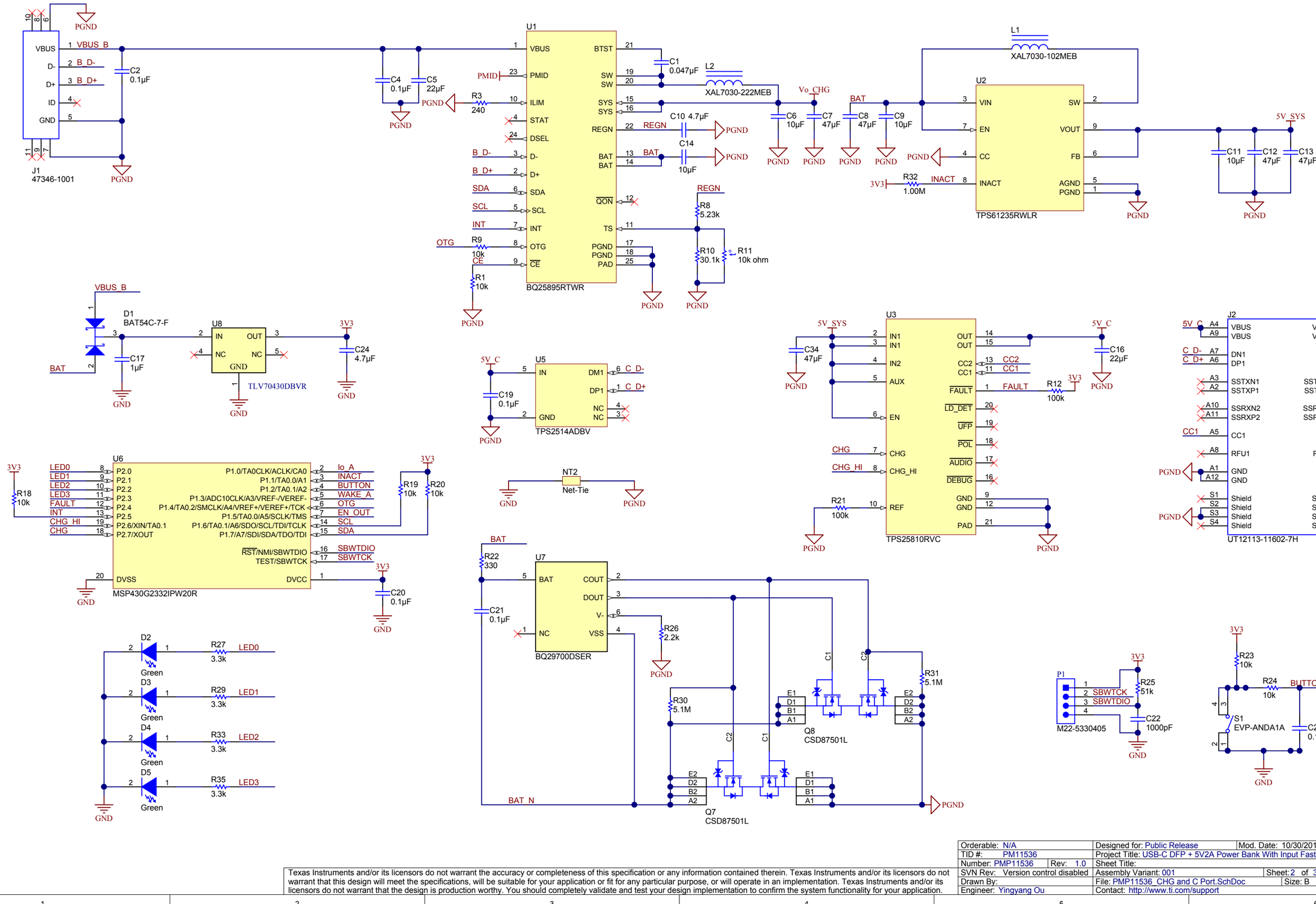
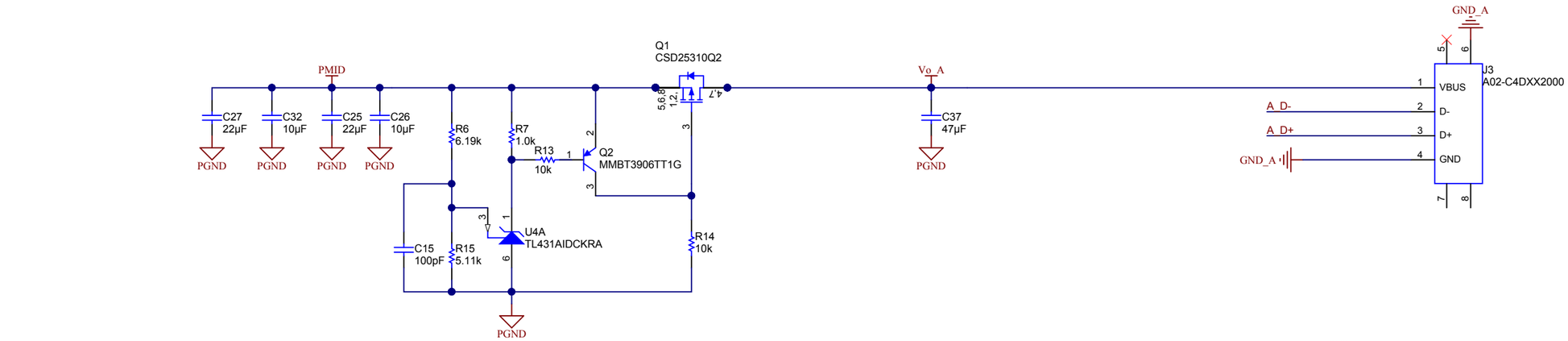
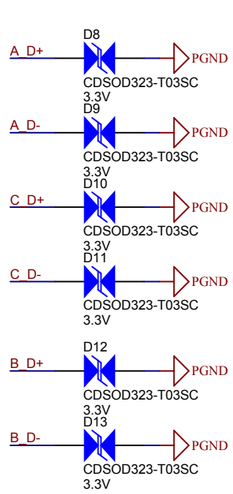
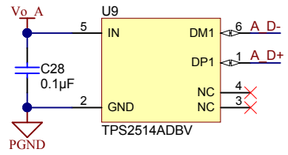
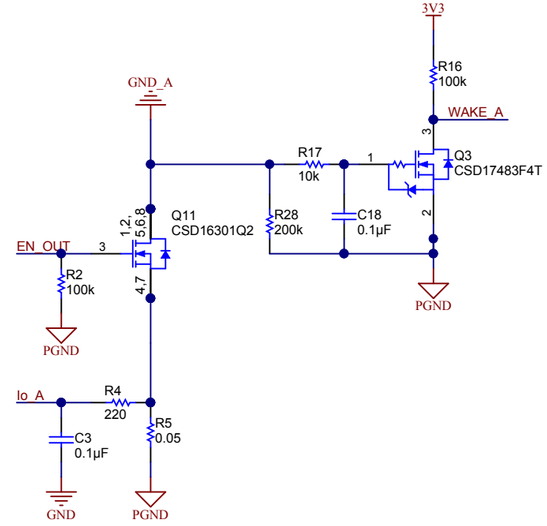


Orderable: N/A		Designed for: Public Release	Mod. Date: 10/30/2015
TID #: PM11536		Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	
Number: PMP11536	Rev: 1.0	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 2 of 3
Drawn By:		File: PMP11536_CHG and C Port.SchDoc	Size: B
Engineer: Yingyang Ou		Contact: http://www.ti.com/support	









Orderable: N/A		Designed for: Public Release	Mod. Date: 11/3/2015
TID #: PM11536		Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	
Number: PMP11536	Rev: 1.0	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 2 of 3
Drawn By:		File: PMP11536_A Port.SchDoc	Size: B
Engineer: Yingyang Ou		Contact: http://www.ti.com/support	

PCB
LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A		Designed for: Public Release	Mod. Date: 10/30/2015
TID #: PM11536		Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	
Number: PMP11536	Rev: 1.0	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 3 of 3
Drawn By:		File: PMP11536_Hardware.SchDoc	Size: B
Engineer: Yingyang Ou		Contact: http://www.ti.com/support	

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